

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2001-110933
 (43)Date of publication of application : 20.04.2001

(51)Int.Cl. H01L 23/12
 H01L 21/60

(21)Application number : 11-286446
 (22)Date of filing : 07.10.1999

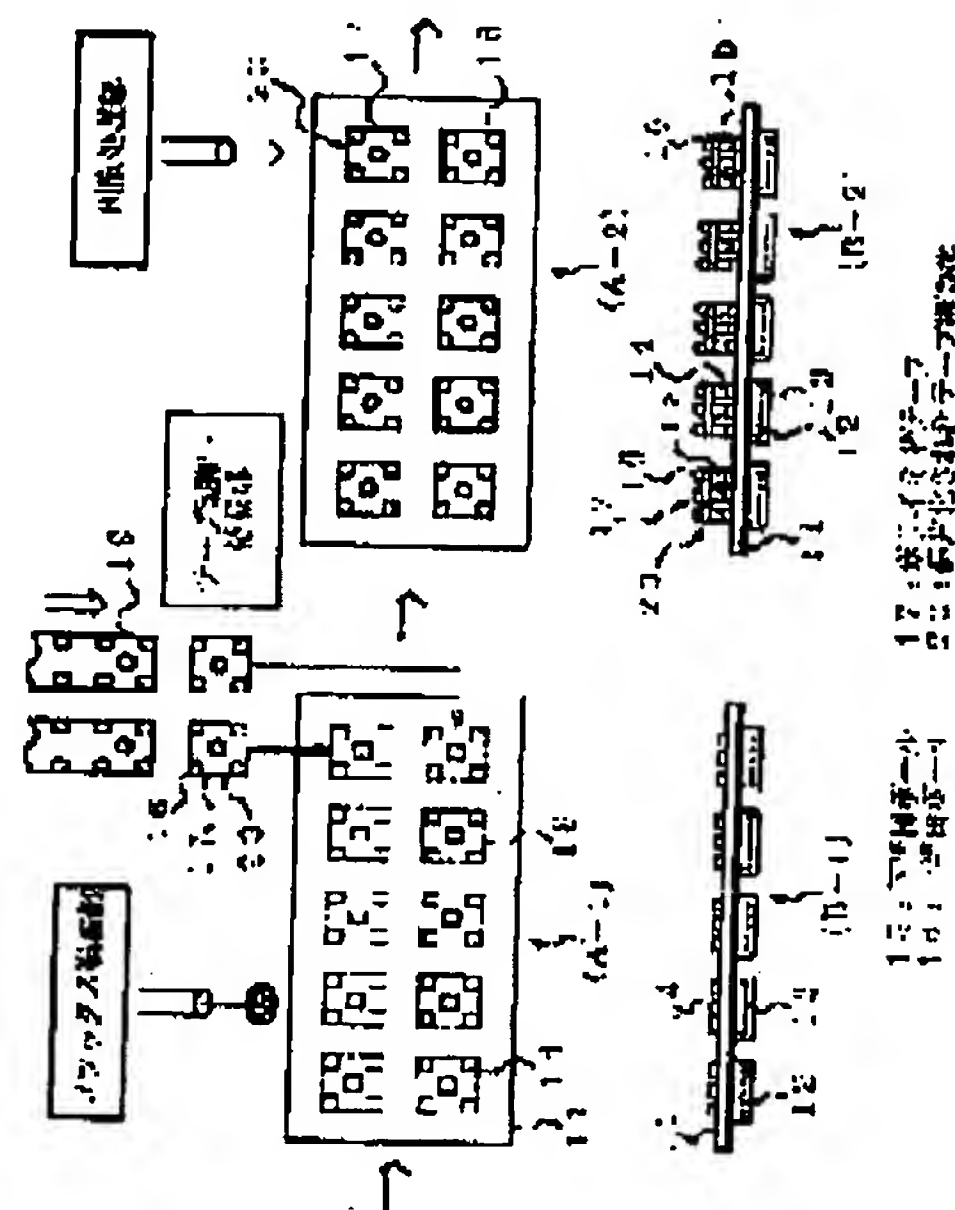
(71)Applicant : NEC KYUSHU LTD
 (72)Inventor : KIMURA NAOTO

(54) SOLDER BALL MOUNTER AND SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a solder ball mouter for less failure in mounting a solder ball while quick mounting is allowed, and to provide a semiconductor device suitable for variation in product types.

SOLUTION: A plurality of first solder balls 15 are formed on one main surface side of an insulating tape 17 while a plurality of second solder balls 16 electrically connected to the first solder balls 15 are formed on the other main surface side, providing a tape structure body 20. The whole tape structure body 20 is mounted on a plurality of electrode pads 14 of an insulating substrate 11.



LEGAL STATUS

[Date of request for examination] 05.09.2000
 [Date of sending the examiner's decision of rejection]
 [Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]
 [Date of final disposal for application]
 [Patent number] 3408473
 [Date of registration] 14.03.2003
 [Number of appeal against examiner's decision of rejection]
 [Date of requesting appeal against examiner's decision of rejection]
 [Date of extinction of right]